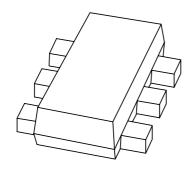
DISCRETE SEMICONDUCTORS

DATA SHEET



PEMB3PNP resistor-equipped double transistor R1 = $4.7 \text{ k}\Omega$, R2 = open

Preliminary specification

2001 Sep 14





PNP resistor-equipped double transistor R1 = 4.7 k Ω , R2 = open

PEMB3

FEATURES

- 300 mW total power dissipation
- Very small 1.6 mm \times 1.2 mm \times 0.55 mm ultra thin package
- · Excellent coplanarity due to straight leads
- Reduces number of components as replacement of two SC-75/SC-89 packaged transistors
- · Reduces required board space
- · Reduces pick and place costs.

APPLICATIONS

- · General purpose switching and amplification
- · Inverter and interface circuits
- · Circuit driver.

DESCRIPTION

PNP resistor-equipped double transistor in a SOT666 plastic package.

MARKING

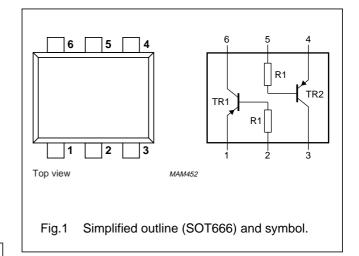
TYPE NUMBER	MARKING CODE	
PEMB3	Z3	

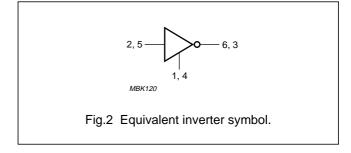
PINNING

PIN	DESCRIPTION		
1, 4	emitter	TR1; TR2	
2, 5	base	TR1; TR2	
6, 3	collector	TR1; TR2	

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V _{CEO}	collector-emitter voltage	-50	٧
I _{CM}	peak collector current	-100	mA
TR1	PNP	_	_
TR2	PNP	_	_
R1	bias resistor	4.7	kΩ





Philips Semiconductors Preliminary specification

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT	
Per transis	Per transistor					
V _{CBO}	collector-base voltage	open emitter	_	-50	V	
V _{CEO}	collector-emitter voltage	open base	_	-50	V	
V _{EBO}	emitter-base voltage	open collector	_	-10	V	
VI	input voltage					
	positive		_	+10	V	
	negative		_	-40	V	
Io	output current (DC)		_	-100	mA	
I _{CM}	peak collector current		_	-100	mA	
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	200	mW	
T _{stg}	storage temperature		-65	+150	°C	
Tj	junction temperature		_	150	°C	
T _{amb}	operating ambient temperature		-65	+150	°C	
Per device	•					
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	300	mW	

Note

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R _{th j-a}	thermal resistance from junction to ambient	notes 1 and 2	416	K/W	

Notes

- 1. Transistor mounted on an FR4 printed-circuit board.
- 2. The only recommended soldering method is reflow soldering.

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^{1.} Transistor mounted on an FR4 printed-circuit board.

Philips Semiconductors Preliminary specification

PNP resistor-equipped double transistor R1 = 4.7 k Ω , R2 = open

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CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Per transis	Per transistor					
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = -50 V	_	_	-100	nA
I _{CEO}	collector cut-off current	I _B = 0; V _{CE} = -50 V	_	_	-1	μΑ
		$I_B = 0$; $V_{CE} = -30 \text{ V}$; $T_j = 150 ^{\circ}\text{C}$	_	_	-50	μΑ
I _{EBO}	emitter cut-off current	I _C = 0; V _{EB} = -5 V	_	_	-100	nA
h _{FE}	DC current gain	$I_C = -1 \text{ mA}; V_{CE} = -5 \text{ V}$	200	_	_	
V _{CEsat}	collector-emitter saturation voltage	$I_C = -5 \text{ mA}; I_B = -0.25 \text{ mA}$	_	_	-100	mV
R1	input resistor		3.3	4.7	6.1	kΩ
C _c	collector capacitance	$I_E = i_e = 0$; $V_{CB} = -10 \text{ V}$; $f = 1 \text{ MHz}$	_	_	3	pF

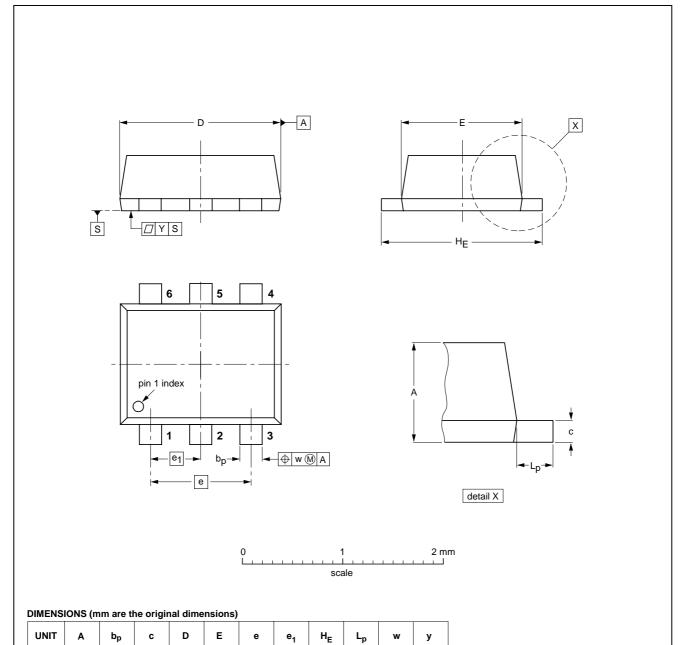
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PACKAGE OUTLINE

Plastic surface mounted package; 6 leads

SOT666



OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT666						-01-01-04 01-08-27

5

1.5

0.1

1.0

0.5

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0.6 0.5

mm

0.27

0.17

0.18

0.08

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DATA SHEET STATUS

DATA SHEET STATUS(1)	PRODUCT STATUS ⁽²⁾	DEFINITIONS
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NOTES

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